A1 Cont'd of a section of an optical disk substrate in which a thin film is formed during film formation by sputtering to a substrate holder.

Page 23, beginning at line 17, please replace the paragraph as follows:

A2 Substrate carriage arms 4a to 4f are connected to the substrate holders 6a to 6f, and the substrate carriage arms 4a to 4f are fixed on a central section 30. The central section 30 is rotated by a driving section not shown herein. In association with this rotation, the substrate holders 6a to 6f can successively set one optical disk substrate in the film-formation chambers 2a to 2e.

Page 25, beginning at line 1, please replace the paragraph as follows:

A3 The optical disk substrate 1 is fixed by an inner mask 11 and an outer mask 12 to the holder section 3, and a film is formed only in an area S of the optical disk substrate exposing from the inner mask 11 as well as from the outer mask 12 (film-formed area).

Page 25, beginning at line 12, to page 26, line 4, please replace the paragraph as follows:

A4 Fig. 3 shows a basic configuration of the holder section 3 described above. On the top is a cross-sectional view of the holder section 3, while on the bottom is a top view of the holder section 3. The cross-sectional view shown in Fig. 3 is taken along the dash line A-A' in the upper view. As shown in Fig. 3, the holder section 3 has the inner mask 11 for fixing the optical disk substrate 1 at a position close to a central point of the optical disk substrate 1 and the outer mask for fixing the optical disk substrate 1 at a position close to a periphery section of the optical disk substrate 1. Both the inner mask 11 and outer mask 12 cover a portion of the optical disk substrate 1, and fix the optical disk substrate 1 holding the optical disk substrate between it and an upper surface of the holder section 3. Because of this configuration, of a surface of the optical disk substrate 1, only portions not fixed by the inner

A4 Contd

mask 11 and outer mask 12 is a film-formed section S. In the first embodiment, the radius of the inner mask 11 is 20 mm, while the radius of the outer mask is 59 mm.

Page 56, beginning at line 5, to page 57, line 4, please replace the paragraph as follows:

Fig. 27 shows a general configuration in the twelfth embodiment of the present invention. In this embodiment, a silicon rubber member 405 with a width H is provided in the edge section 401e having the configuration used in the ninth embodiment described above and shown in Fig. 18. The width H is defined herein as a length of the silicon rubber member 405 in the radial direction of the substrate 404 as shown in Fig. 27. With the

A5

configuration shown in Fig. 27, samples of substrate holder No. 22 to No. 27 are manufactured as shown in Fig. 26, and firm formation is performed on each of the samples under the same conditions as those in the eleventh embodiment, and assessment is carried out. As shown in Fig. 26, with the configuration according to this embodiment, a warping amount of a substrate can be suppressed to around 100 μm, and also damages to a substrate by the edge section 401e of the substrate holder can be prevented. When the width H of the silicon rubber member is less than 0.1 mm, mechanical load to the edge section 401e due to deformation of a substrate can not be evaded, and when the width H is 0.5 mm or more, suppression of deformation of a substrate can not be expected. Although a silicon rubber member is used for the edge section 401e in this embodiment, the effects obtained in this embodiment are not limited to the one obtained when the silicon rubber is used, and any material such as a molded resin body may be used so far as the hardness is lower than that of a substrate.